

TECHNICAL

INSTRUCTIONS

DATA SHEETS

CUPOMEX MAT

INTRODUCTION

AUROMEX CUPOMEX MAT is a newly acid mat copper plating process. It is specially designed for nickel-free mat finish decorative products such as jewellery items, watch cases and spectacle frame. Deposits are fine, highly ductile and low internal stress.

DEPOSIT CHARACTERISTICS

- * Good throwing and covering power
- * Uniform distribution
- * Economical, easy to operate
- * Low internal stress and highly ductile
- * High efficiency

PLATING BATH PREPARATION

Materials required for making-up 100 litres bath are as follows :-

Copper Sulphate	10 - 12 Kgs
Sulphuric Acid (S.G. 1.84)	8 - 10 Litres
Sodium Chloride, pure	6 - 8 Gms.
CUPOMEX MAT	1 - 1.5 Litres

MAKE-UP PROCEDURES :- (100 LITRES)

- 1) Fill to a clean plating tank 2/3 of the required final volume with distilled or deionised water.
- 2) Add in 10 litres Sulphuric acid carefully.
- 3) Add in 12 kgs. copper sulphate, stir until completely dissolved.
- 4) Filtration with carbon treatment.
- 5) Finally add in 1 litre Cupomex MAT, then the solution is ready to use.

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OPERATING CONDITIONS

	<u>UNIT</u>	RANGE	<u>OPTIMUM</u>
Copper Sulphate	g/l	100-120	100
Copper Metal	g/l	25-30	25
Sulphuric Acid (S.G.1.84)	mls/litre	80-100	100
Chloride Ion (CI)	mg/litre	60-80	80
Temperature	°C	25-35	25
Agitation		Air or Cathode agitation	
Cathode currenty density AMP./d m^2		1-4	3
Anode	Phosphorous anode		

SOLUTION MAINTENANCE

CUPOMEX MAT : 4,000 Ampre-hours needs to replenish 1 litre CUPOMEX MAT.

- COPPER METAL : Normally, it is replenished by dissolving the phosphorous anode. Too low copper metal content will cause burning in high current density area. Suggest periodically solution analysis, and adding copper sulphate for adjustment.
- SULPHURIC ACID : Its main purpose is for conductivity and dissolving the copper anode. Too high or low content will affect the deposit result.

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